Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**PAD FUNCTION:**

1. **N. OE**
2. **D0**
3. **D1**
4. **D2**
5. **D3**
6. **D4**
7. **D5**
8. **D6**
9. **D7**
10. **GND**
11. **CP**
12. **Q7**
13. **Q6**
14. **Q5**
15. **Q4**
16. **Q3**
17. **Q2**
18. **Q1**
19. **Q0**
20. **VCC**

**.067”**

**.055”**

**2 1 20 19**

**9 10 11 12**

**3**

**4**

**5**

**6**

**7**

**8**

**18**

**17**

**16**

**15**

**14**

**13**

**MASK**

**REF**

**HC 574**

**Top Material: Al**

**Backside Material: Si**

**Bond Pad Size = .004” X .004”**

**Backside Potential: VCC or FLOAT**

**Mask Ref: HC 574**

**APPROVED BY: DK DIE SIZE .055” X .067” DATE: 3/21/19**

**MFG: TEXAS INSTRUMENTS THICKNESS .025” P/N: 54HC574**

**DG 10.1.2**

#### Rev B, 7/1